

CH3D30120H

Silicon Carbide Schottky Diode



V_{RRM}	=	1200	V
I_F ($T_c \leq 135^\circ C$)	=	39	A
Q_c	=	99	nC

Features

- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- Positive Temperature Coefficient on V_F
- Temperature-independent Switching
- 175°C Operating Junction Temperature

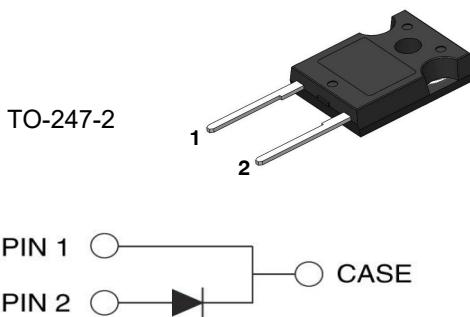
Benefits

- Replace Bipolar with Unipolar Device
- Reduction of Heat Sink Size
- Parallel Devices Without Thermal Runaway
- Essentially No Switching Losses

Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor drive, PV Inverter, Wind Power Station

Package



Part Number	Package	Marking
CH3D30120H	TO-247-2	CH3D30120H

Maximum Ratings

Symbol	Parameter	Value	Unit	Test Conditions	Note
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V	$T_c = 25^\circ C$	
V_{RSM}	Surge Peak Reverse Voltage	1200	V	$T_c = 25^\circ C$	
V_R	DC Blocking Voltage	1200	V	$T_c = 25^\circ C$	
I_F	Forward Current	39 30	A	$T_c \leq 135^\circ C$ $T_c \leq 149^\circ C$	
I_{FSM}	Non-Repetitive Forward Surge Current	230	A	$T_c = 25^\circ C, t_p = 10ms$, Half Sine Wave	
P_{tot}	Power Dissipation	384	W	$T_c = 25^\circ C$	Fig.3
T_c	Maximum Case Temperature	149	°C		
T_J, T_{STG}	Operating Junction and Storage Temperature	-55 to 175	°C		
	TO-247 Mounting Torque	1	Nm	M3 Screw	
I_{FRM}	Repetitive Forward Surge Current	200	A	$T_c = 25^\circ C, t_p = 10ms$, Half Sine Wave	
E_{AS}	Single Pulse Avalanche Energy (Note 1)	225	mJ	Single Pulse, L=2mH, IAS=15A	

Electrical Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V _F	Forward Voltage	1.45 2.2	1.8 2.5	V	I _F = 30A, T _J = 25°C I _F = 30A, T _J = 175°C	Fig.1
I _R	Reverse Current	10 50	50 500	μA	V _R = 1200V, T _J = 25°C V _R = 1200V, T _J = 175°C	Fig.2
C	Total Capacitance	1890 145 103	/	pF	V _R = 0V, T _J = 25°C, f = 1MHz V _R = 400V, T _J = 25°C, f = 1MHz V _R = 800V, T _J = 25°C, f = 1MHz	Fig.5
Q _c	Total Capacitive Charge	160	/	nC	V _R = 800V, I _F = 30A di/dt = 200A/μs, T _J = 25°C	Fig.4

Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Note
R _{θJC}	Thermal Resistance from Junction to Case	0.39	°C/W	Fig.6
R _{θJA}	Thermal Resistance from Junction to Ambient	80	°C/W	
T _{sold}	Soldering Temperature	260	°C	

Typical Performance

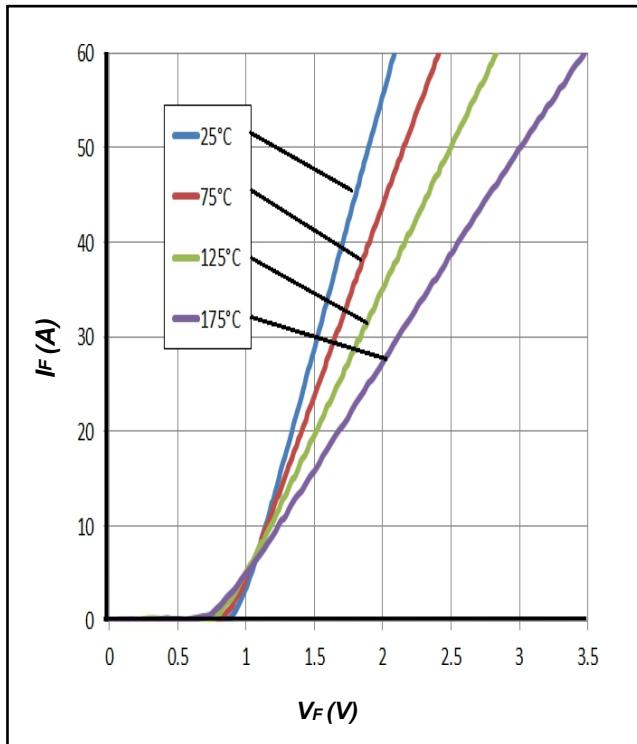


Figure 1. Forward Characteristics

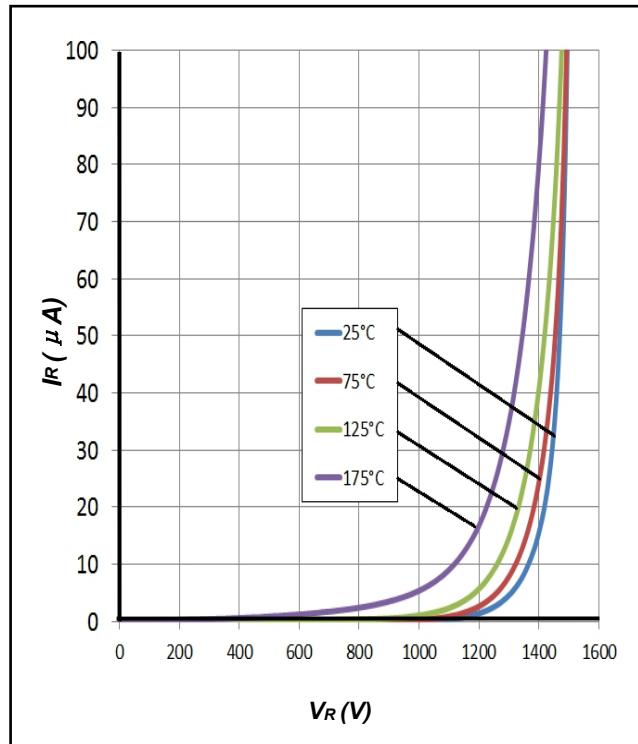


Figure 2. Reverse Characteristics

Typical Performance

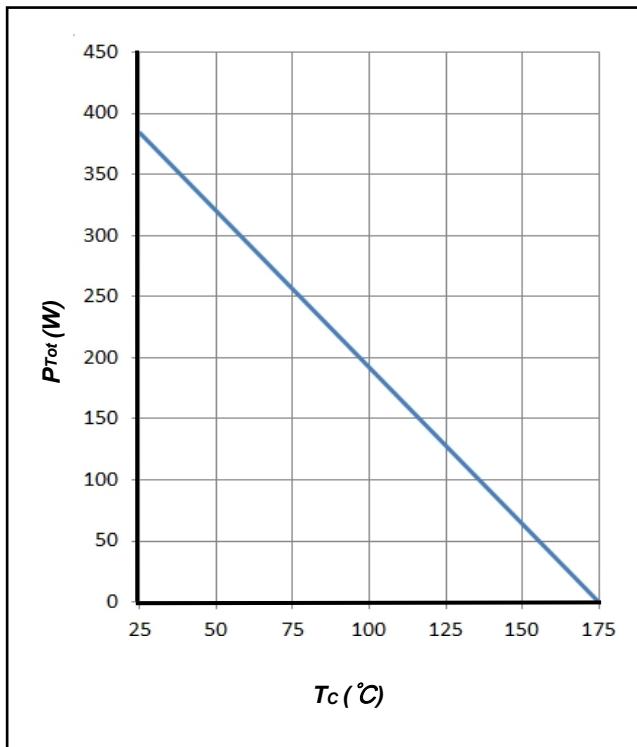


Figure 3. Power Derating

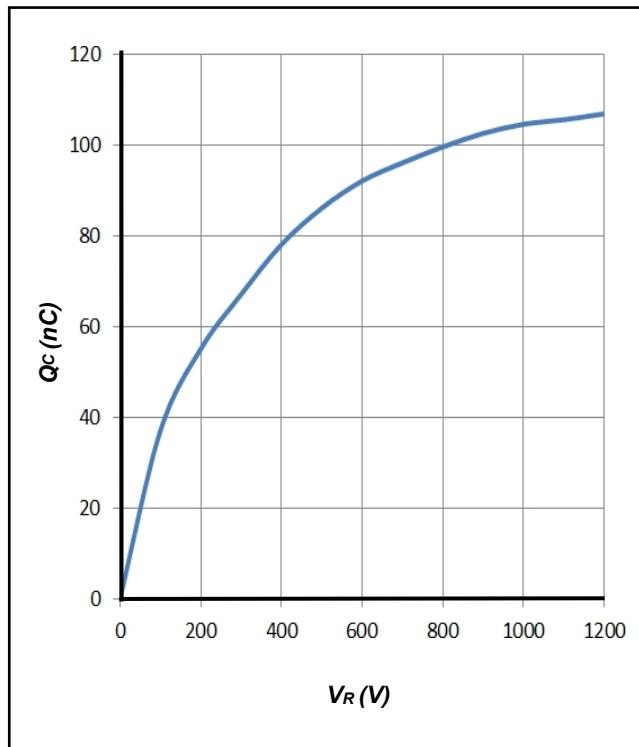


Figure 4. Total Capacitive Charge vs. Reverse Voltage

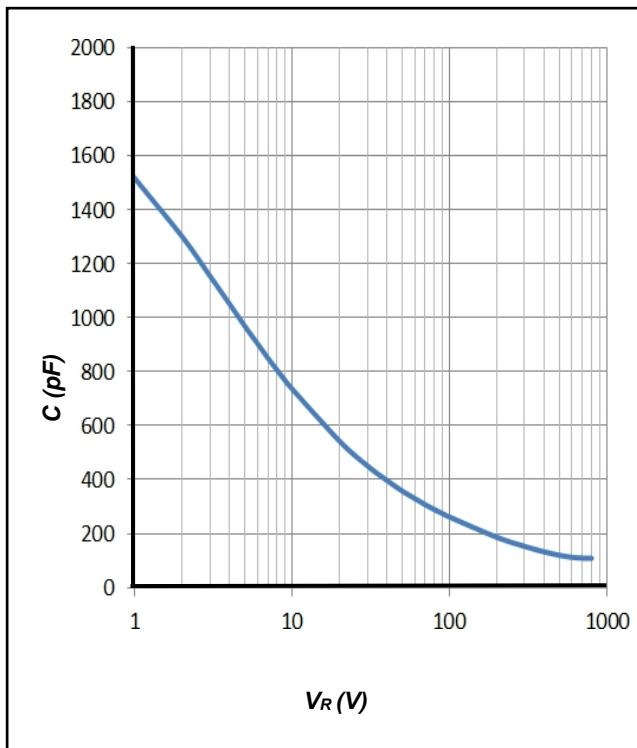


Figure 5. Total Capacitance vs. Reverse Voltage

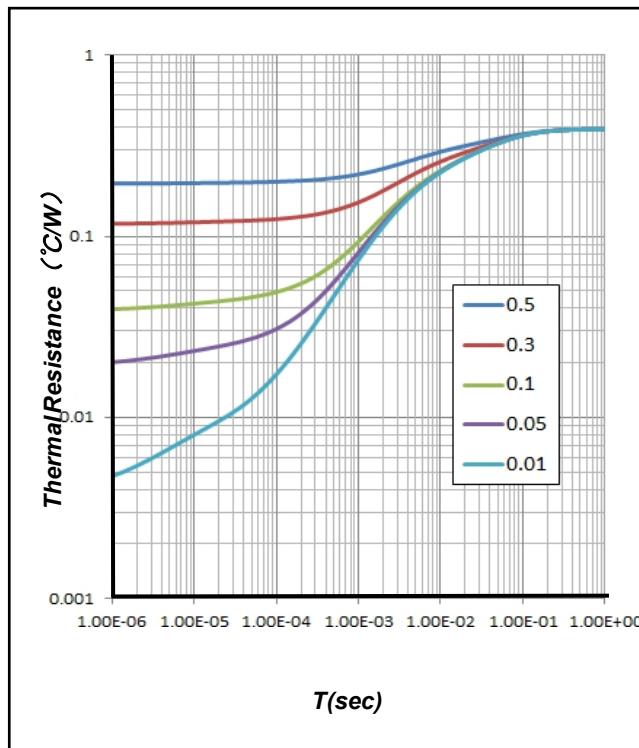
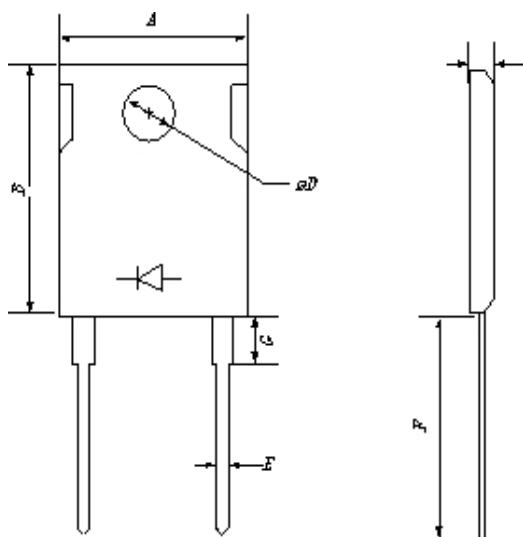


Figure 6. Transient Thermal Impedance

Package Dimensions

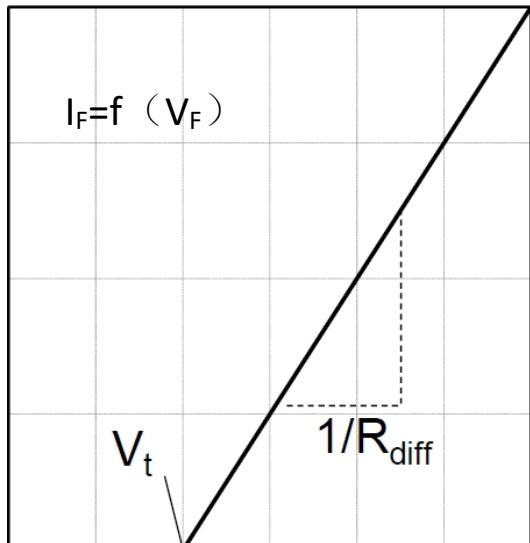
Package TO-247-2



Symbol	Min. (mm)	Typ. (mm)	Max. (mm)
A	14.18	15.75	17.33
B	18.45	20.5	22.55
C	4.50	5.00	5.50
D	3.15	3.50	3.85
E	1.08	1.20	1.32
F	18.27	20.30	22.33

Simplified Diode Model

Equivalent IV Curve for Model



Mathematical Equation

$$V_F = V_t + I_F \times R_{\text{diff}}$$

$$V_t = -0.00115 \times T_j + 0.984 \text{ [V]}$$

$$R_{\text{diff}} = 5.76 \times 10^{-7} \times T_j^2 + 6.47 \times 10^{-5} \times T_j + 0.0171 \text{ [\Omega]}$$

Note:

T_j = Diode Junction Temperature In Degrees Celsius,
valid from 25°C to 175°C

I_F = Forward Current

Less than 60A